

**AMENDMENTS TO THE SPECIFICATION:**

**Please amend the Abstract as shown hereinbelow:**

**ABSTRACT**

This is a cooler for dissipating heat away from an electronic device (A). The cooler includes a liquid cooling mechanism (B), a forcible air cooling mechanism (C) and a substrate (D). The liquid cooling mechanism includes a set of metal pipes (20-21) connected to a pump (3) with an impeller (16) to transfer cooling liquid to a liquid channel (4). The forcible air cooling mechanism (C) includes a fan (25) discharging air onto a radiating fin (37) located on the set of metal pipes (20-21). The substrates (D) is in fluid communication with the forcible air cooling mechanism (C) and the liquid cooling mechanism (B) and in direct contact with the electronic device (A) so as to remove heat away from the electronic device (A). Onto a heat sink (1) to be in contact with an electronic device (A), a liquid channel (4) is provided. Metal pipes (20) and (21) connecting a pump (3) which transfers a cooling liquid by the rotation of an impeller (16) to the liquid channel (4) are placed to construct a liquid cooling mechanism (B). A radiating fin (37) is placed on the outer surface of the metal pipes (20) and (21), and a fan (25) which discharge the air from within the metal pipes (20) and (21) having the radiating fin (37) placed thereon and from within the body is placed to construct a forcible air cooling mechanism (C). By placing magnets (29) and (39) on the fan (25) and the impeller (16), respectively, the constructions of the rotation driving mechanism are simplified to make it possible to provide a cooler in a compact form.